

32/36-bit Data Bus
Dynamic RAM Card

MF14M1-L17ATXX
 MF14M1-L27ATXX
 MF18M1-L17ATXX
 MF18M1-L27ATXX

Connector Type

Two-piece 88-pin

DESCRIPTION

These DRAM CARDS are developed based on JEIDA DRAM CARD GUIDELINE Ver. 2.1.

These cards are made using industry standard 1 M × 4 and 1 M × 1 Dynamic RAM and interface IC's in TSOP.

FEATURES

- All inputs except RAS inputs are buffered.
- Standard card size : 54mm (W) × 85.6mm (L) × 3.3mm (T)
- 88pin 2 piece connector type.
- RAS only refresh mode, CAS before RAS refresh mode and Page mode functions are available.
- Extended refresh is available. (128ms/1024cycle)

APPLICATIONS

Main/expansion memory unit for Personal Computer. Laser-Printer, FAX etc.

PRODUCT LIST

Product No.	Item Type name	Memory capacity	Data Bus width (bits)	Access time (tRAC) (ns)	Connector type	Number of pins	Outline drawing
No. 1	MF14M1-L17ATXX	4 MB	32 (without parity)	70	Two-piece	88	88P-001
No. 2	MF14M1-L27ATXX		36 (with parity)	70			
No. 3	MF18M1-L17ATXX	8 MB	32 (without parity)	70			
No. 4	MF18M1-L27ATXX		36 (with parity)	70			

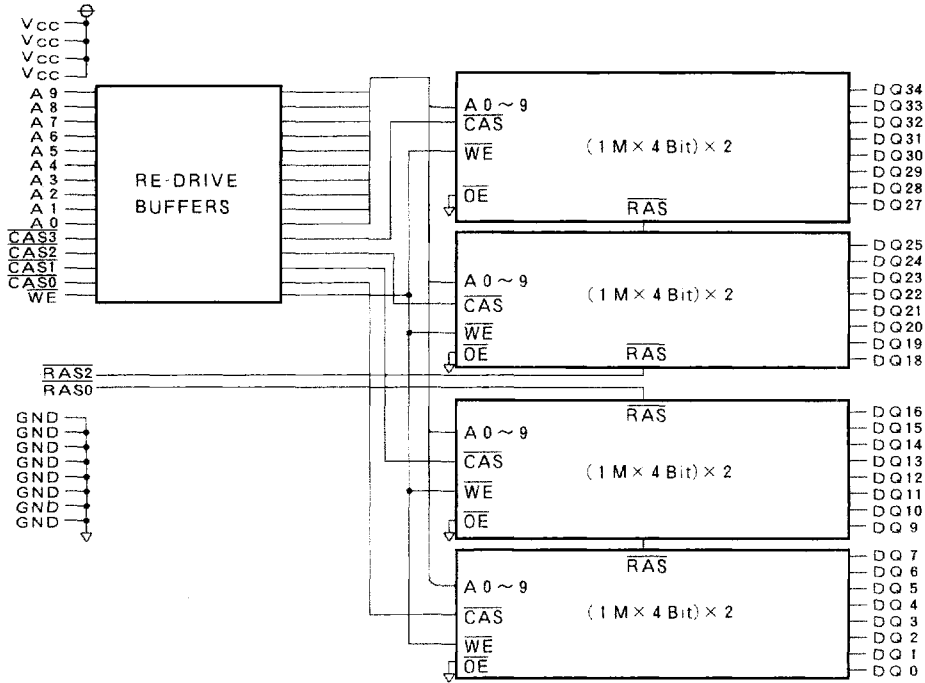
PIN ASSIGNMENT

Pin No.	Symbol	Function	Pin No.	Symbol	Function	
1	GND	Ground	45	GND	Ground	
2	DQ 0	Data I/O	46	DQ18	Data I/O	
3	DQ 1		47	DQ19		
4	DQ 2		48	DQ20		
5	DQ 3		49	DQ21		
6	DQ 4		50	DQ22		
7	DQ 5		51	DQ23		
8	DQ 6		52	DQ24		
9	V _{CC}		Power supply voltage	53		DQ25
10	DQ7	Data I/O	54	DQ26		
11	NC	No connection	55	NC	No connection	
12	DQ 8	Data I/O (NC for No. 1, 3)	56	GND	Ground	
13	A 0	Address input	57	A 1	Address input	
14	A 2		58	A 3		
15	V _{CC}	Power supply voltage	59	A 5		
16	A 4	Address input	60	A 7		
17	NC	No connection	61	A 9	No connection	
18	A 6	Address input	62	NC		
19	A 8		63	GND	Ground	
20	NC	No connection	64	NC	No connection	
21	NC		65	RAS1	Row address strobe 1 (NC for No. 1, 2)	
22	RAS0	Row address strobe 0	66	CAS2	Column address strobe 2	
23	CAS0	Column address strobe 0	67	GND	Ground	
24	CAS1	Column address strobe 1	68	CAS3	Column address strobe 3	
25	NC	No connection	69	RAS3	Row address strobe 3 (NC for No. 1, 2)	
26	RAS2	Row address strobe 2	70	WE	Write enable	
27	V _{CC}	Power supply voltage	71	PD 1	Presence detect 1	
28	PD 2	Presence detect 2	72	PD 3	Presence detect 3	
29	PD 4	Presence detect 4	73	GND	Ground	
30	PD 6	Presence detect 6	74	PD 5	Presence detect 5	
31	NC	No connection	75	PD 7	Presence detect 7	
32	NC		76	PD 8	Presence detect 8	
33	DQ17	Data I/O (NC for No. 1, 3)	77	NC	No connection	
34	DQ 9	Data I/O	78	PD 9	Presence detect 9	
35	NC	No connection	79	DQ35	Data I/O (NC for No. 1, 3)	
36	DQ10	Data I/O	80	DQ27	Data I/O	
37	V _{CC}	Power supply voltage	81	DQ28		
38	DQ11	Data I/O	82	DQ29		
39	DQ12		83	DQ30		
40	DQ13		84	DQ31		
41	DQ14		85	DQ32		
42	DQ15		86	DQ33		
43	DQ16		87	DQ34		
44	GND		Ground	88	GND	Ground

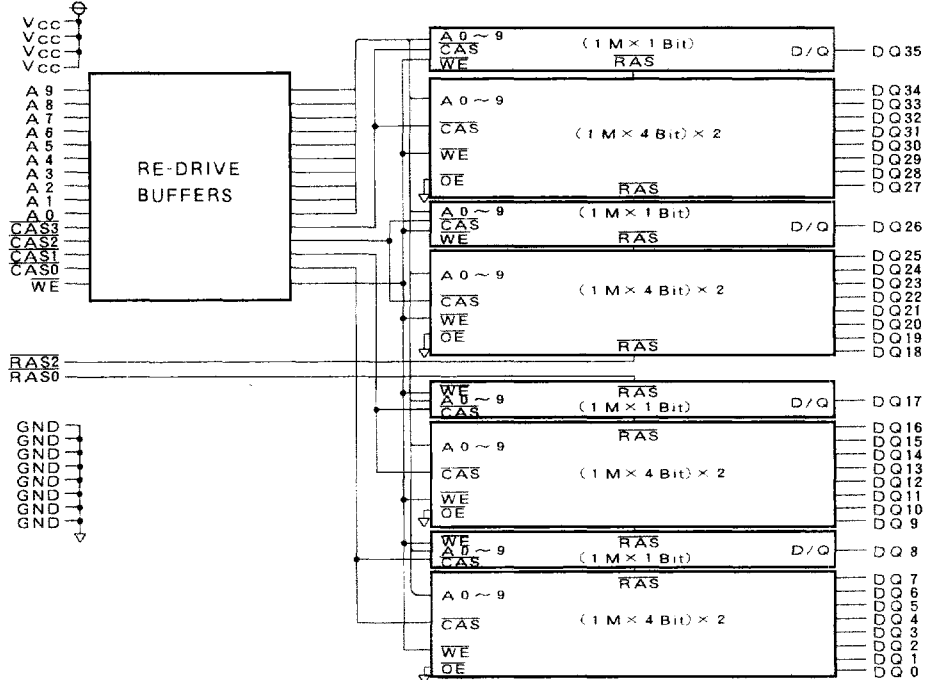
PD Pin Table

Product No.	PD 1	PD 2	PD 3	PD 4	PD 5	PD 6	PD 7	PD 8	PD 9
No. 1	GND	NC	GND	GND	NC	GND	NC	NC	NC
No. 2	GND	NC	GND	GND	NC	GND	NC	NC	NC
No. 3	GND	NC	GND	GND	GND	GND	NC	NC	NC
No. 4	GND	NC	GND	GND	GND	GND	NC	NC	NC

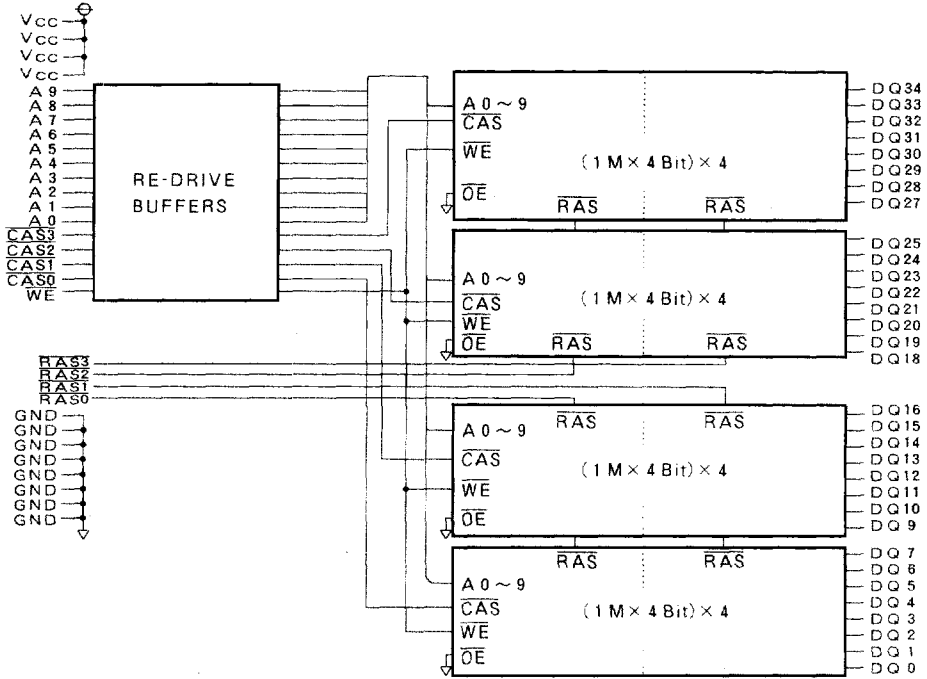
BLOCK DIAGRAM (No.1)



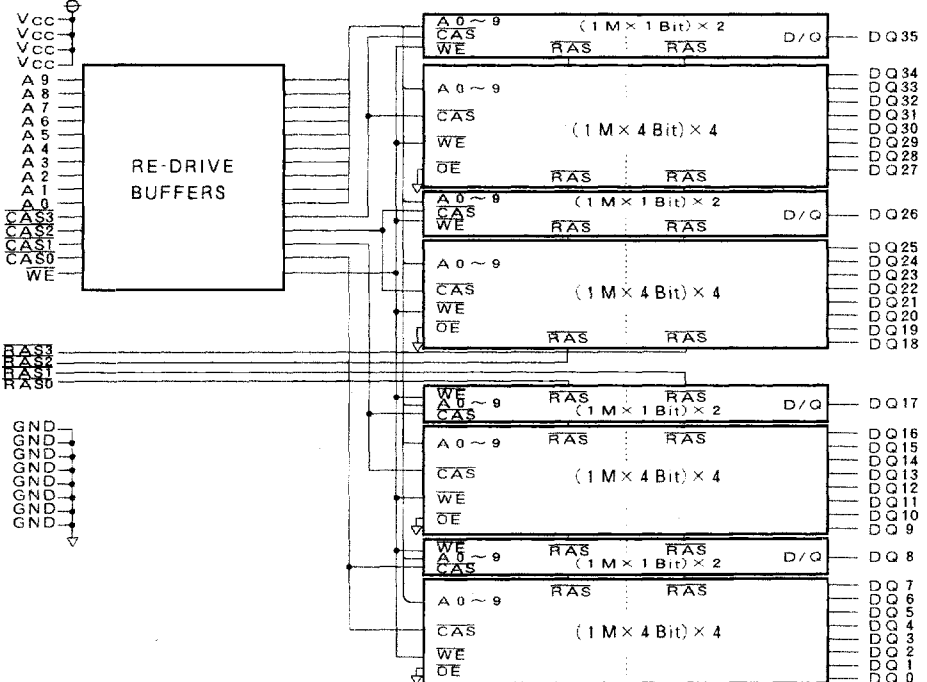
BLOCK DIAGRAM (No.2)



BLOCK DIAGRAM (No.3)



BLOCK DIAGRAM (No.4)



DYNAMIC RAM CARDS

FUNCTION TABLE

Operation	input					input/output		Refresh	Note
	RAS	CAS	WE	Row Address	Column Address	input	output		
Read	ACT	ACT	NAC	APD	APD	OPN	VLD	YES	Page mode identical
Early write	ACT	ACT	ACT	APD	APD	VLD	OPN	YES	
RAS only refresh	ACT	NAC	DNC	APD	DNC	DNC	OPN	YES	
CAS before RAS refresh	ACT	ACT	NAC	DNC	DNC	DNC	OPN	YES	
Standby	NAC	DNC	DNC	DNC	DNC	DNC	OPN	NO	

Note 1 : ACT : active, NAC : nonactive, DNC : don't care, VLD : valid, APD : applied, OPN : open
 Don't be active more than two RASs at the same time.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V _{CC}	Supply voltage	With respect to GND	-0.5~7	V
V _I	Input voltage		-0.5~V _{CC} +0.5 (7V max.)	V
V _O	Output voltage		-0.5~7	V
I _O	Output current	T _a =25°C	50	mA
P _d	Power dissipation		8	W
T _{opr}	Operating temperature		0~55	°C
T _{stg}	Storage temperature		-40~80	°C

RECOMMENDED OPERATING CONDITIONS (T_a= 0~55°C, unless otherwise noted): (Note 2)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
V _{CC}	Supply voltage	4.75	5	5.25	V
GND	Supply voltage	0	0	0	V
V _{IL}	Low input voltage	0		0.8	V
V _{IH}	High input voltage	0.7×V _{CC}		V _{CC}	V

Note 2 : With respect to GND

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ELECTRICAL CHARACTERISTICS ($T_a = 0 \sim 55^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 5\%$, $\text{GND} = 0\text{V}$): (Note 3)

Symbol	Parameter	Test condition	Limits								Unit	
			Min.				Typ.	Max.				
			No. 1	No. 2	No. 3	No. 4		No. 1	No. 2	No. 3		No. 4
V_{OH}	High output voltage	$I_{OH} = -5\text{mA}$	2.4					V_{CC}				V
V_{OL}	Low output voltage	$I_{OL} = 4.2\text{mA}$	0					0.4				V
I_{OZ}	Off-stage output current	$0\text{V} \leq V_{OUT} \leq V_{CC}$	-10	-10	-20	-20		10	10	20	20	μA
I_I	Input current	$0\text{V} \leq V_{IN} \leq V_{CC}$ Other input pins = 0V	-40	-60	-40	-60		40	60	40	60	μA
$I_{CC1(AV)}$	Average supply current from V_{CC} , operating (Note 4, 5)	$\overline{\text{RAS}}$, $\overline{\text{CAS}}$ cycling $t_{RC} = t_{WC} = \text{min}$, output open						800	1120	820	1150	mA
$I_{CC2(AV)}$	Supply current from V_{CC} , standby	$\overline{\text{RAS}} = \overline{\text{CAS}} = V_{IH}$, output open						20	28	36	52	mA
		$\overline{\text{RAS}} = \overline{\text{CAS}} \geq V_{CC} - 0.2\text{V}$, other input pins $\geq V_{CC} - 0.2\text{V}$ or $\leq 0.2\text{V}$, output open						5	6	9	10	
$I_{CC3(AV)}$	Average supply current from V_{CC} , refreshing (Note 4)	$\overline{\text{RAS}}$ cycling, $\overline{\text{CAS}} = V_{IH}$ $t_{RC} = \text{min}$, output open						800	1120	820	1150	mA
$I_{CC4(AV)}$	Average supply current from V_{CC} , Page-Mode (Note 4, 5)	$\overline{\text{RAS}} = V_{IL}$, $\overline{\text{CAS}}$ cycling $t_{RC} = \text{min}$, output open						960	1240	980	1270	mA
$I_{CC6(AV)}$	Average supply current from V_{CC} , $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh mode (Note 4)	$\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ refresh cycling $t_{RC} = \text{min}$, output open						720	1040	740	1070	mA

Note 3 : Current flowing into a CARD is positive, out is negative.

4 : $I_{CC1(AV)}$, $I_{CC3(AV)}$, $I_{CC4(AV)}$ and $I_{CC6(AV)}$ are dependent on cycle rate. Specified values are obtained at the fastest cycle rate.

5 : $I_{CC1(AV)}$ and $I_{CC4(AV)}$ are dependent on output loading. Specified values are obtained with the outputs open.

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SWITCHING CHARACTERISTICS ($T_a = 0 \sim 55^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 5\%$, $GND = 0\text{V}$): (Note 6)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tCAC	Access time from $\overline{\text{CAS}}$ (Note 7, 8)		27	ns
tRAC	Access time from $\overline{\text{RAS}}$ (Note 7, 9)		70	ns
tCAA	Column Address access time (Note 7, 10)		45	ns
tOFF	Output disable time after $\overline{\text{CAS}}$ high (Note 11)	0	25	ns

Note 6 : An initial pause of 500 μ sec is required after power-up followed by any 8 $\overline{\text{RAS}}$ or $\overline{\text{RAS}}/\overline{\text{CAS}}$ cycles before proper device operation is achieved. Note that $\overline{\text{RAS}}$ may be cycled during the initial pause. And any 8 $\overline{\text{RAS}}$ or $\overline{\text{RAS}}/\overline{\text{CAS}}$ cycles are required after prolonged periods of $\overline{\text{RAS}}$ inactivity before proper device operation is achieved.

7 : Measured with a load circuit equivalent to 2 TTL loads and 100pF.

8 : Assume that $t_{\text{RCD}} \geq t_{\text{RCD}(\text{max})}$ and $t_{\text{ASC}} \geq t_{\text{ASC}(\text{max})}$.

9 : Assume that $t_{\text{RCD}} \leq t_{\text{RCD}(\text{max})}$ and $t_{\text{RAD}} \leq t_{\text{RAD}(\text{max})}$.

10 : Assume that $t_{\text{RAD}} \geq t_{\text{RAD}(\text{max})}$ and $t_{\text{ASC}} \leq t_{\text{ASC}(\text{max})}$.

11 : tOFF(max) define the time at which the output achieves the high impedance state ($|I_{\text{out}}| \leq 10\ \mu\text{A}$ or $20\ \mu\text{A}$) and are not reference to $V_{\text{OH}(\text{min})}$ or $V_{\text{OL}(\text{max})}$.

TIMING REQUIREMENTS ($T_a = 0 \sim 55^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 5\%$, $GND = 0\text{V}$): (Note 12, 13)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tREF	Refresh cycle time (1024 cycles)		128	ms
tRP	$\overline{\text{RAS}}$ high pulse width	60		ns
tRCD	Delay time, $\overline{\text{RAS}}$ low to $\overline{\text{CAS}}$ low (Note 14)	20	43	ns
tCRP	Delay time, $\overline{\text{CAS}}$ high to $\overline{\text{RAS}}$ low (Note 15)	20		ns
tRPC	Precharge to $\overline{\text{CAS}}$ active time	0		ns
tCPN	$\overline{\text{CAS}}$ high pulse width	10		ns
tRAD	Column address delay time from $\overline{\text{RAS}}$ low (Note 16)	15	25	ns
tASR	Row address setup time before $\overline{\text{RAS}}$ low	10		ns
tASC	Column address setup time before $\overline{\text{CAS}}$ low (Note 17)	5	13	ns
tRAH	Row address hold time after $\overline{\text{RAS}}$ low	10		ns
tCAH	Column address hold time after $\overline{\text{CAS}}$ low	15		ns
tT	Transition time (Note 18)	3	50	ns

Note 12 : The timing requirements are assumed tT = 5 ns.

13 : $V_{\text{IH}(\text{min})}$ and $V_{\text{IL}(\text{max})}$ are reference levels for measuring timing of input signals.

14 : tRCD(max) is specified as a reference point only. If tRCD is greater than tRCD(max), access time is defined as tCAC and tCAA.

15 : tCRP requirement is applicable for all $\overline{\text{RAS}}/\overline{\text{CAS}}$ cycles.

16 : tRAD(max) is specified as reference point only. If tRAD \geq tRAD(max) and tASC \leq tASC(max), access time is assumed by tCAA for read cycle.

17 : tASC(max) is specified as a reference point only of address access time.

18 : tT is measured between $V_{\text{IH}(\text{min})}$ and $V_{\text{IL}(\text{max})}$.

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Read and Refresh Cycles

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tRC	Read cycle time	140		ns
tRAS	$\overline{\text{RAS}}$ low pulse width	70	10000	ns
tCAS	$\overline{\text{CAS}}$ low pulse width	20	10000	ns
tCSH	$\overline{\text{CAS}}$ hold time after $\overline{\text{RAS}}$ low	70		ns
tRSH	$\overline{\text{RAS}}$ hold time after $\overline{\text{CAS}}$ low	30		ns
tRCS	Read Setup time before $\overline{\text{CAS}}$ low	5		ns
tRCH	Read hold time after $\overline{\text{CAS}}$ high	0		ns
tRRH	Read hold time after $\overline{\text{RAS}}$ high	10		ns

Write Cycle (Early Write)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tWC	Write cycle time	140		ns
tRAS	$\overline{\text{RAS}}$ low pulse width	70	10000	ns
tCAS	$\overline{\text{CAS}}$ low pulse width	20	10000	ns
tCSH	$\overline{\text{CAS}}$ hold time after $\overline{\text{RAS}}$ low	70		ns
tRSH	$\overline{\text{RAS}}$ hold time after $\overline{\text{CAS}}$ low	30		ns
twCS	Write Setup time before $\overline{\text{CAS}}$ low	5		ns
twCH	Write hold time after $\overline{\text{CAS}}$ low	15		ns
tDS	Data setup time	10		ns
tdH	Data hold time after $\overline{\text{CAS}}$ low	25		ns

Page Mode Cycle (Read, Early Write)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tPC	Read, Write cycle time	55		ns
tCP	$\overline{\text{CAS}}$ high pulse width (Note 19)	10	18	ns
tRAS	$\overline{\text{RAS}}$ low pulse width	125	100000	ns

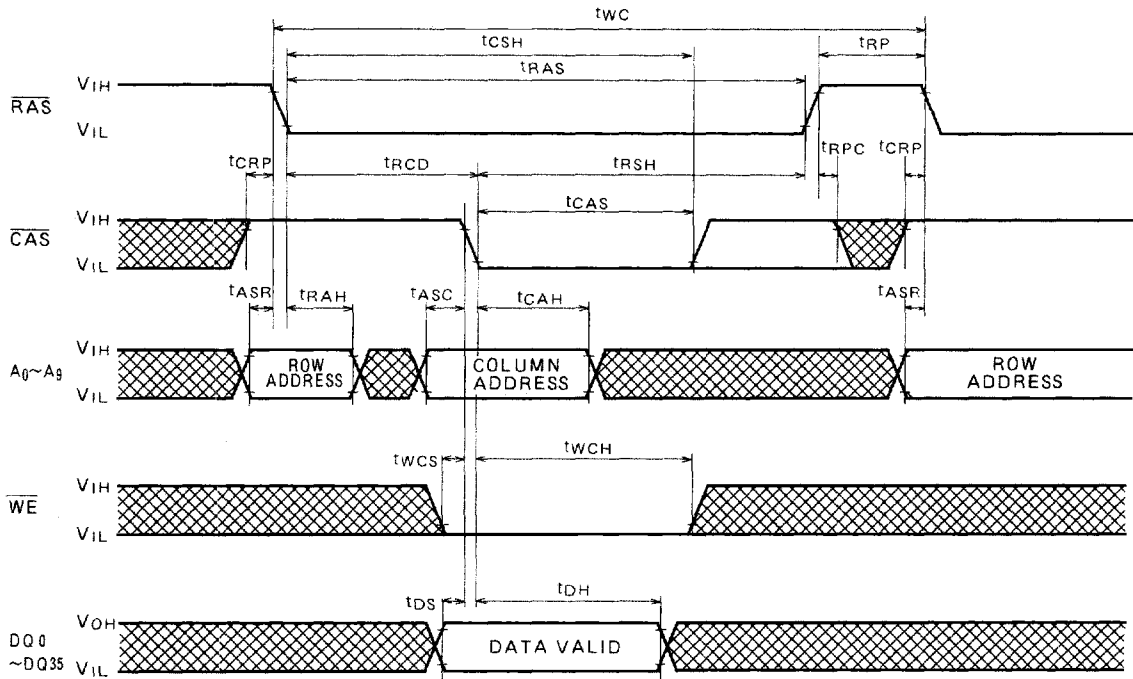
Note 19 : tCP(max) is specified as a reference point only.

CAS before RAS Refresh Cycle (Note 20)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tCSR	$\overline{\text{CAS}}$ setup time for $\overline{\text{CAS}}$ before RAS refresh	20		ns
tCHR	$\overline{\text{CAS}}$ hold time for $\overline{\text{CAS}}$ before RAS refresh	15		ns

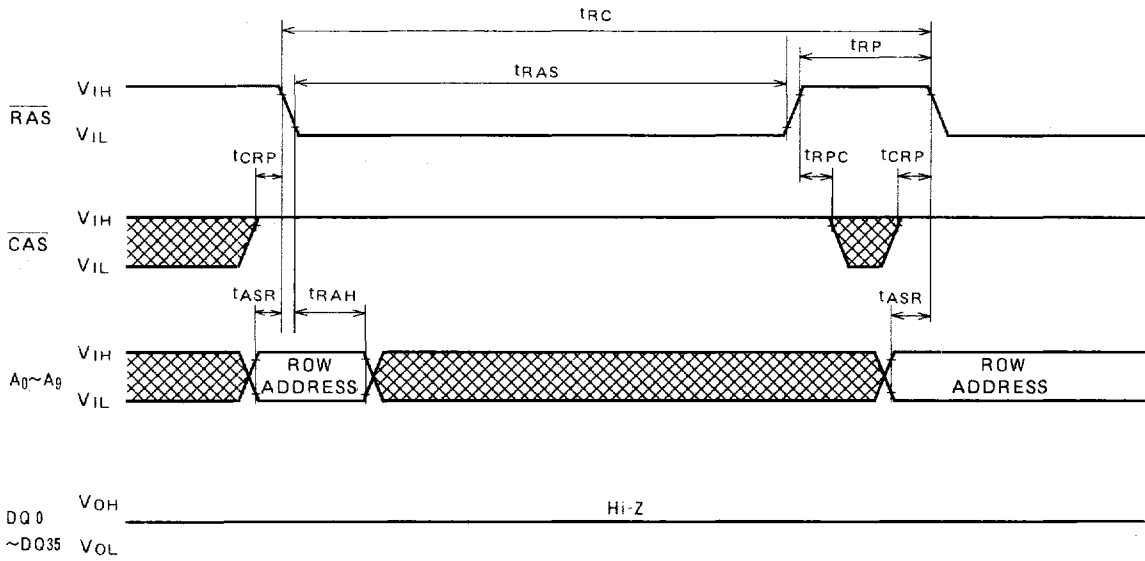
Note 20 : Eight or more $\overline{\text{CAS}}$ before RAS cycles are necessary for proper operation of $\overline{\text{CAS}}$ before RAS refresh mode.

Early Write Cycle



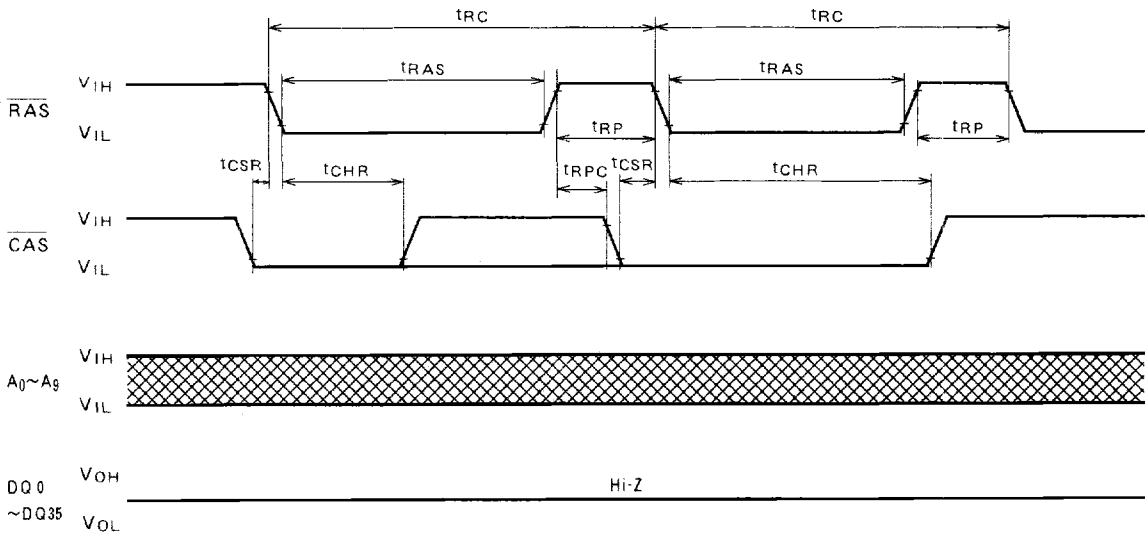
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RAS only Refresh Cycle (Note 22)



Note 22 : \overline{WE} = don't care.

CAS before RAS Refresh Cycle (Note 23)



Note 23 : $\overline{WE} = V_{IH}$

Page-Mode Early Write Cycle

